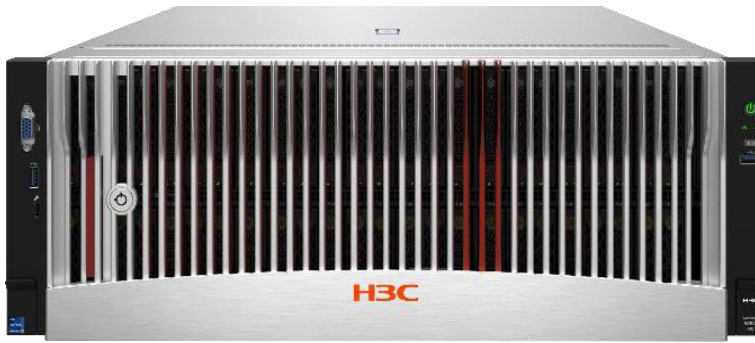




H3C UniServer R6900 G6 Server

Flagship Compute for Business-Critical Computing



Extraordinary performance

- 4 Intel® Xeon® 4th generation scalable processors
- 64 DIMM DDR5 5600MT/s
- 6 SW or 10 DW GPU

Excellent scalability and flexibility

- Modular design
- Flexible combination of 4 drive backplanes
- Easy-to-expand PCIe5.0 I/O slots

Leading Low-Carbon Energy-Saving Technologies

- Intelligent dynamic energy saving for processors
- Smart wind heat dissipation system
- Intelligent power supply system

Product Overview

H3C UniServer R6900 G6 server is a new generation of 4U quad-socket rack server independently developed by H3C based on the Intel Eagle Stream platform. It's design has been fully optimized on the basis of the previous generation product, reaching a new height in terms of performance, scalability and low-carbon energy saving. It is another benchmark quad-socket server product after the G5 product. Ideal for mission-critical data-intensive applications such as large-scale virtualization, databases, in-memory computing, data analytics, data warehousing, business intelligence, and ERP.

Product features

Ultra Performance

H3C UniServer R6900 G6 utilizes Intel® Xeon® 4th Gen Scalable processors, supports DDR5 memory at 5600MT/s, and can accommodate up to six enterprise-class dual-width accelerator cards, delivering astonishing computational power for data centers.

Flexible expansion

In response to ever-evolving business demands, the modular design of R6900 G6 ensures adaptability. For the storage, four drive expander modules support various drive specifications—including HDD, SSD, NVMe, and E1.S—enabling customers to select based on specific needs. With an all-PCIe 5.0 design, the overall system provides up to 22 PCIe 5.0 slots to meet diverse I/O expansion requirements.

Stability & Reliability

Under high-load operations in data-intensive scenarios, heat dissipation is critical for server stability. R6900 G6 employs a dual-layer symmetric cooling solution within its 4U chassis, ensuring efficient thermal management for components ranging from the processor and memory to drives and I/O devices, guaranteeing reliability even under extreme conditions.

Additionally, R6900 G6 integrates energy-saving technologies such as intelligent dynamic processor power optimization, smart airflow cooling, and adaptive power supply systems. These innovations reduce power consumption while meeting performance demands, helping enterprise clients build greener, more sustainable data centers.

Technical specifications

CPU	4 4th Generation Intel®Xeon® Sapphire Rapids SP series 60 Cores for each Processor with 350W power consumption
Chipset	Intel®C741
Memory	64 DDR5 RDIMM Slots, 5600 MT/s Data Rate
RAID controller	Optional HBA cards and RAID controllers based on standard PCIe slots Supports dual M.2 configuration with RAID 1 for os installation disks Supports SD card as boot disk.
FBWC	8 GB Cache Supports Supercapacitor protection
Storage	50 SAS/SATA HDD/SSD Drives 32 NVMe Drives Supports PCIe NVMe storage accelerator card and dual hot-swappable SATA M.2 Kit (Optional)
Network	1 Onboard 1Gbps Management Network Port Optional expansion via OCP 3.0 x16 slots, supporting 4×1GE copper ports or 2×10GE copper/fiber ports or 2×25GE fiber ports PCIe Standard Slots for 1/10/25/40/100Gb Ethernet Adapter or 100/200Gb InfiniBand card
Expansion slots	Up to 10 PCIe 5.0 x 16 Standard Slots Up to 22 PCIe 5.0 x 8 Standard Slots Up to 2 Onboard OCP 3.0 Slots
Ports	2 VGA Rear Port (1 Front, 1 Rear) 3 USB 3.0 Ports (1 Front, 2 Rear), 3 USB 2.0 Ports (1 Front, 2 Internal) 1 Management Port , 1 serial port, 1 Type-C port, Power-Button, UID
GPU	Up to 6 double-width or 10 single-width GPU cards
Optical drive	External Optical Disk Drive, Optional
Management	H3C HDM Standard License, iFIST (embedded), H3C Advanced Feature Package License (optional, requires licenses), H3C UniSystem (requires download) Optional LCD touchable model
Security	Intelligent Front Security Bezel TCM/TPM2.0 Silicon Root of Trust Two-Factor Authentication Secure decommissioning function

Power supplies	Up to 4 Platinum-grade 800W/850W/1300W/1600W/2000W/2400W power supplies, supporting N+N redundancy configuration Titanium-grade option available*: Optional 1600W 336V/48V DC power supply module with N+N redundancy support Supports 8 N+1 hot-swappable redundant fans, allowing optional selection of 8038 or 8056 fans as needed
Standards	CE, UL, FCC, VCCI, CB, etc.
Operating temperature	5°C to 45° C (41°F to 113°F) (Operating temperature support varies depending on different configurations. For details, please refer to the detailed product technical documentation description.)
Dimensions (H×W×D)	4U Height Without a security bezel: 174.8×447×830mm (6.88×17.60×32.68 in) With a security bezel: 174.8×447×858mm (6.88×17.60×33.78 in)

- *The options may be different depending on the specific requirement. Restrictions and limitations may apply. To confirm availability, refer to related user guide or visit H3C website <https://www.h3c.com/en/home/htb/>.



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